in the

1

As a below named inventor, I hereby declare that:

My	r residence,	post of	lice address	and citi	izenship a	re as stated	below nex	t to my i	nanic.
----	--------------	---------	--------------	----------	------------	--------------	-----------	-----------	--------

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled <u>STRUCTURE AND METHOD FOR MANUFACTURING A SEMICONDUCTOR</u>

#### 

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by an amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s) 8-289568	Japan	31/10/1996	Priority Cl (Yes)	laimed Mo
(Number)	(Country)	(Day/Month/Year Filed)		
			Yes	No
(Number)	(Country)	(Day/Month/Year Filed)		
			Yes	No
(Number)	(Country)	(Day/Month/Year Filed)		

I hereby claim the benefit under Title 35, United State Code, §120 of any United States application(s) listed below and, insofat as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56(a) which occurred between the filing date of the prior application and the national or PCF international filing date of this application:

(Application Serial No.)	(Filing Date)	(Status - patented, pending, abandoned)
(Application Script No.)	(Filing Date)	(Status - patented, pending, abandoned)

I hereby appoint as my attorney and agent Aaron B. Karas, Reg. No. 18,923, Samson Helfgott, Reg. No. 23,072, Leonard Cooper Reg. No. 27,625 and Emma Shleifer, Reg. No. 29,734 to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Address all correspondence to:

HELFGOTT & KARAS P.C.

60th Floor Empire State Building New York, New York 10118-0110 Telephone No. (212) 643-5000

Thereby declare that all statements made herein of my own knowledge are true and that all statements made on informa-

## UNITED STATES

Docket No.

ADDITIONAL INVENTORS FOR DECLARATION/ASSIGNMENT Full name of additional towenter Akihiko Inventor's signature Residence Tokyo, Vapan 27/10/1997 Date Citizenship Japanese Post Office Address 3-15-8, Minami-Senzoku, Ohta-ku, Tokyo, Japan Full name of additional inventor \_\_\_\_\_ Second Inventor's signature\_\_\_\_\_ Date\_\_\_ Residence\_ Citizenship\_\_\_\_ Post Office Address Full name of additional inventor Inventor's signature Date \_\_\_ Residence \_\_\_\_\_Citizenship\_\_\_\_\_ Post Office Address Full name of additional inventor Second Inventor's signature\_\_\_\_ Date Residence Citizenship Post Office Address Full name of additional inventor Inventor's signature \_\_\_\_\_ Date \_\_\_\_ Residence Citizenship Post Office Address Full name of additional inventor \_\_\_\_\_ Second Inventor's signature\_\_\_\_\_ Date Residence Citizenship Post Office Address Full name of additional inventor Inventor's signature \_\_\_\_\_ Date Residence Citizenship Post Office Address Full name of additional inventor Second Inventor's signature\_\_\_\_ Date Residence Citizenship Post Office Address\_\_\_\_\_ Full name of additional inventor Second Inventor's signature Date Misi--nahin

Ü Ü W. M

Filed Via Express Mail Rec. No.: EL 639 744 757 US

On: JUNE 25, 2001

LINDA E. HASTINGS

Any fee due as a result of this paper, not covered by an enclosed check, may be charged on Deposit Acct. No. 08-1634.

#### Attorney Docket No.: SOH 14.569A

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor :

Norihiro IWAI, et al.

Serial No.

•

:

Filed

June 25, 2001

Title

MANUFACTURING A SEMICONDUCTOR

STRUCTURE AND METHOD FOR

**OPTICAL WAVEGUIDE** 

Examiner

•

Group Art Unit

.

Assistant Commissioner for Patents Washington, D.C. 20231

### **SUB-POWER OF ATTORNEY**

SIR:

I, Samson Helfgott, attorney of record herein, do hereby grant a sub-power of attorney to Linda S. Chan, Reg. No. 42,400; Michael I. Markowitz, Reg. No. 30,659; Brian S. Myers, Reg. No. 46,947; and Harris A. Wolin, Reg. No. 39,432 to act and sign in my behalf in the above-referenced application.

Respectfully submitted,

Samson Helfgott/ Reg. No. 23,072

HELFGOTT & KARAS, P.C. 60TH FLOOR EMPIRE STATE BUILDING NEW YORK, NEW YORK 10118 (212) 643-5000 DOCKET NO.:SOH 14.569A SH:MIM:1hda:SOH14569A